

## N-Channel Enhancement Mode Power MOSFET

### General Description

The series of Power MOSFETs use advanced technology and design. This high voltage MOSFET fits Switched applications.

### Features

- High speed switching
- Intrinsic capacitances and Qg minimized
- 100% Avalanche Tested

### Application

- Switched applications

$V_{DS\ min@T_{jmax}}$	1850	V
$R_{DS(ON)TYP}$	6	$\Omega$
$I_D$	2.9	A
$Q_g$	33	nC



Schematic diagram

### Package Marking And Ordering Information

Device	Device Package	Marking
NCE3N170PF	TO-3PF	NCE3N170PF



TO-3PF

Table 1. Absolute Maximum Ratings ( $T_J=25^\circ\text{C}$ )

Parameter	Symbol	NCE3N170PF	Unit
Drain-Source Voltage ( $V_{GS}=0V$ )	$V_{DS}$	1700	V
Gate-Source Voltage ( $V_{DS}=0V$ ) DC	$V_{GS}$	$\pm 30$	V
Continuous Drain Current at $T_c=25^\circ\text{C}$	$I_{D(DC)}$	2.9	A
Continuous Drain Current at $T_c=100^\circ\text{C}$	$I_{D(DC)}$	2.03	A
Pulsed drain current (Note 1)	$I_{DM(pluse)}$	8.7	A
Maximum Power Dissipation ( $T_c=25^\circ\text{C}$ )	$P_D$	88	W
Derate above $25^\circ\text{C}$		0.58	W/ $^\circ\text{C}$
Single pulse avalanche energy (Note 2)	$E_{AS}$	210	mJ
Single pulse avalanche current (Note 2)	$I_{AS}$	2.9	A
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55...+175	$^\circ\text{C}$

\* limited by maximum junction temperature

**Table 2. Thermal Characteristic**

Parameter	Symbol	NCE3N170	Unit
Thermal Resistance, Junction-to-Case (Maximum)	$R_{thJC}$	1.7	$^{\circ}\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient (Maximum)	$R_{thJA}$	50	$^{\circ}\text{C}/\text{W}$

**Table 3. Electrical Characteristics ( $T_J=25^{\circ}\text{C}$  unless otherwise noted)**

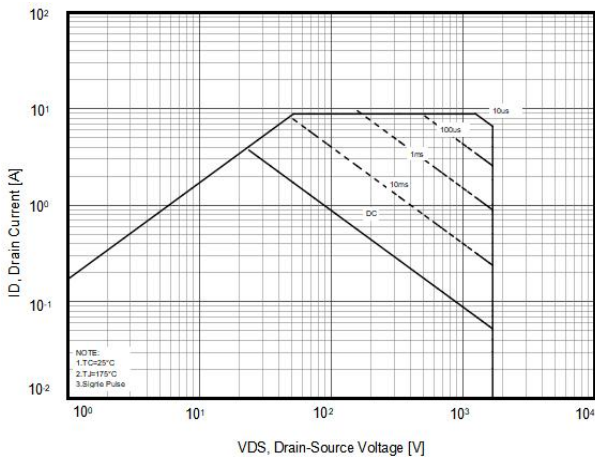
Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>On/off states</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=1\text{mA}$	1700			V
Zero Gate Voltage Drain Current( $T_c=25^{\circ}\text{C}$ )	$I_{DSS}$	$V_{DS}=1700V, V_{GS}=0V$			1	$\mu\text{A}$
Zero Gate Voltage Drain Current( $T_c=125^{\circ}\text{C}$ )	$I_{DSS}$	$V_{DS}=1700V, V_{GS}=0V$			100	$\mu\text{A}$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm 30V, V_{DS}=0V$			$\pm 100$	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	3	4	5	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=1.45A$		6	8	$\Omega$
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{DS}=40V, V_{GS}=0V,$ $F=1.0\text{MHz}$		1700		pF
Output Capacitance	$C_{oss}$			60		pF
Reverse Transfer Capacitance	$C_{rss}$			3.3		pF
Total Gate Charge	$Q_g$	$V_{DS}=1350V, I_D=1.45A,$ $V_{GS}=10V$		33		nC
Gate-Source Charge	$Q_{gs}$			7.7		nC
Gate-Drain Charge	$Q_{gd}$			14		nC
Intrinsic gate resistance	$R_G$	$f = 1\text{MHz open drain}$		2		$\Omega$
<b>Switching times</b>						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=850V, I_D=1.45A,$ $R_G=3\Omega, V_{GS}=10V$		22		nS
Turn-on Rise Time	$t_r$			8		nS
Turn-Off Delay Time	$t_{d(off)}$			48		nS
Turn-Off Fall Time	$t_f$			49		nS
<b>Source- Drain Diode Characteristics</b>						
Source-drain current(Body Diode)	$I_{SD}$	$T_C=25^{\circ}\text{C}$			2.9	A
Pulsed Source-drain current(Body Diode)	$I_{SDM}$				8.7	A
Forward On Voltage	$V_{SD}$	$T_J=25^{\circ}\text{C}, I_{SD}=2.9A, V_{GS}=0V$		0.8	1.1	V
Reverse Recovery Time	$t_{rr}$	$T_J=25^{\circ}\text{C}, I_F=2.9A,$ $di/dt=100A/\mu\text{s}$		1500		nS
Reverse Recovery Charge	$Q_{rr}$			5.7		$\mu\text{C}$
Peak Reverse Recovery Current	$I_{rrm}$			7.5		A

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

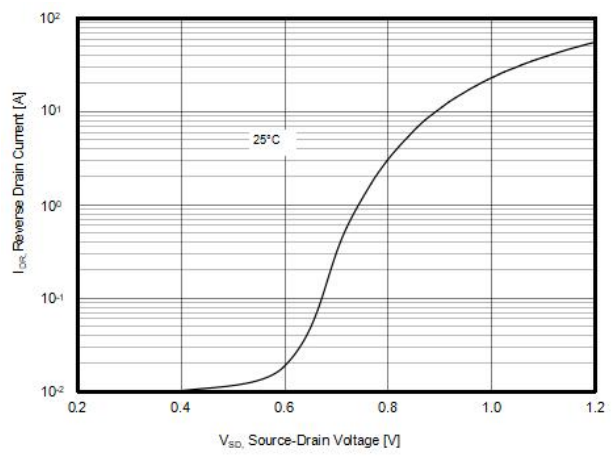
2.  $T_J=25^{\circ}\text{C}, V_{DD}=50V, V_G=10V, R_G=25\Omega$

## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

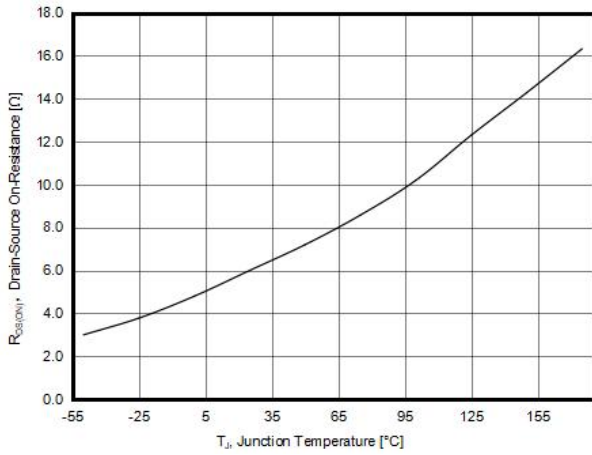
**Figure1. Safe operating area**



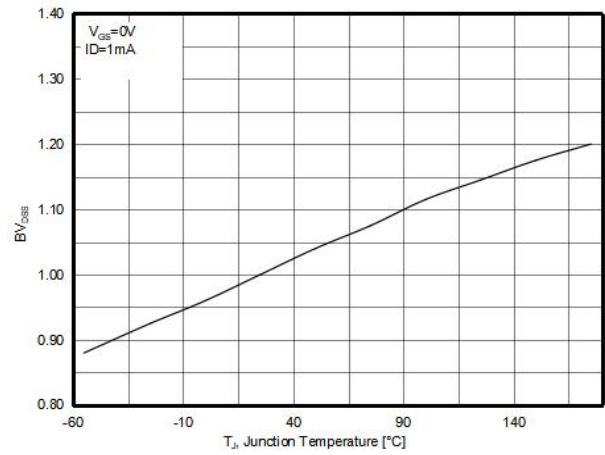
**Figure2. Source-Drain Diode Forward Voltage**



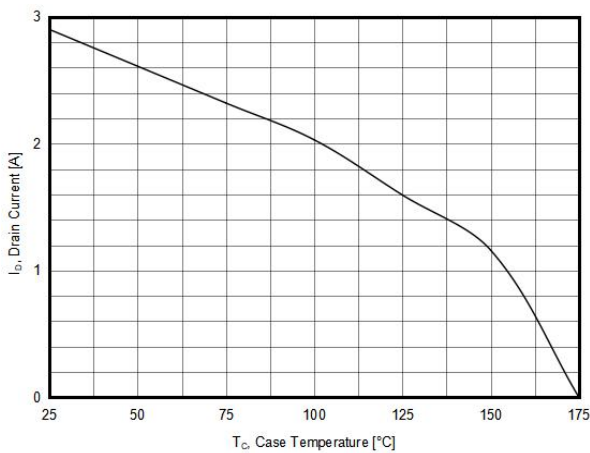
**Figure3. RDS(ON) vs Junction Temperature**



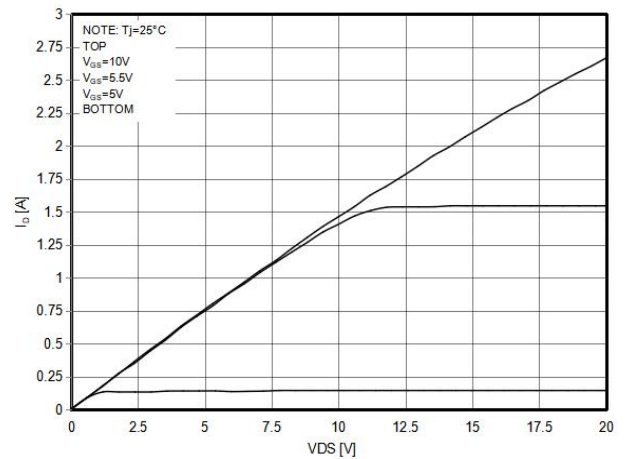
**Figure4. BVDS vs Junction Temperature**



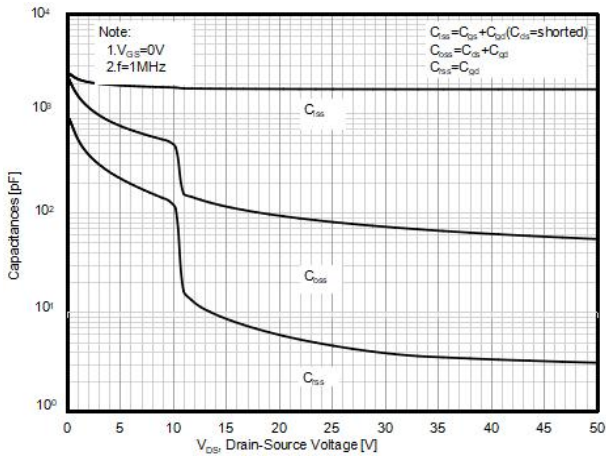
**Figure5. Maximum ID vs Junction Temperature**



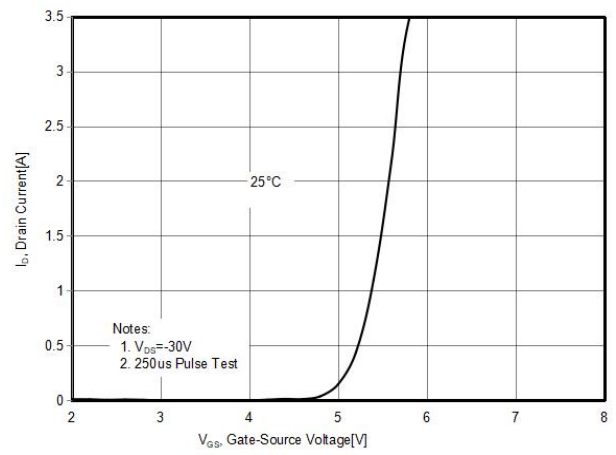
**Figure6. Output characteristics**



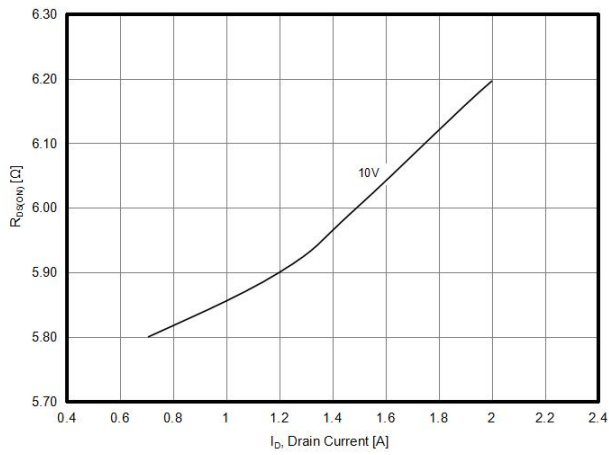
**Figure7. Capacitance**



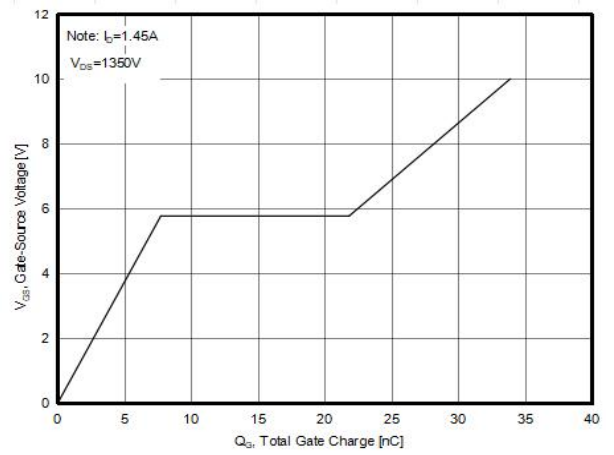
**Figure8. Transfer characteristics**



**Figure9. Static drain-source on resistance**



**Figure9. Gate charge waveforms**

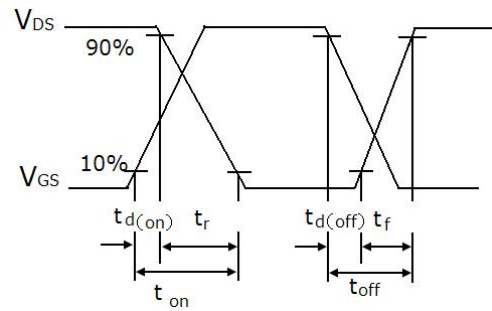


## Test circuit

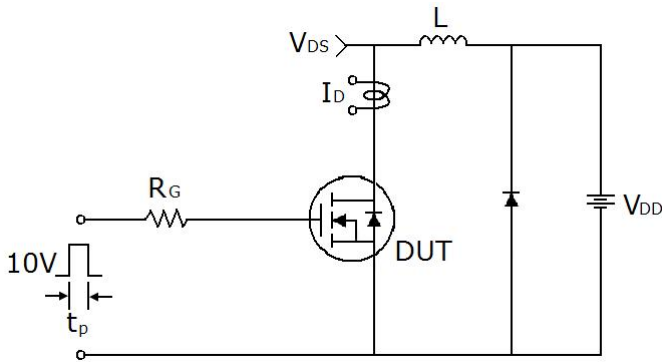
### 1) Gate charge test circuit & Waveform



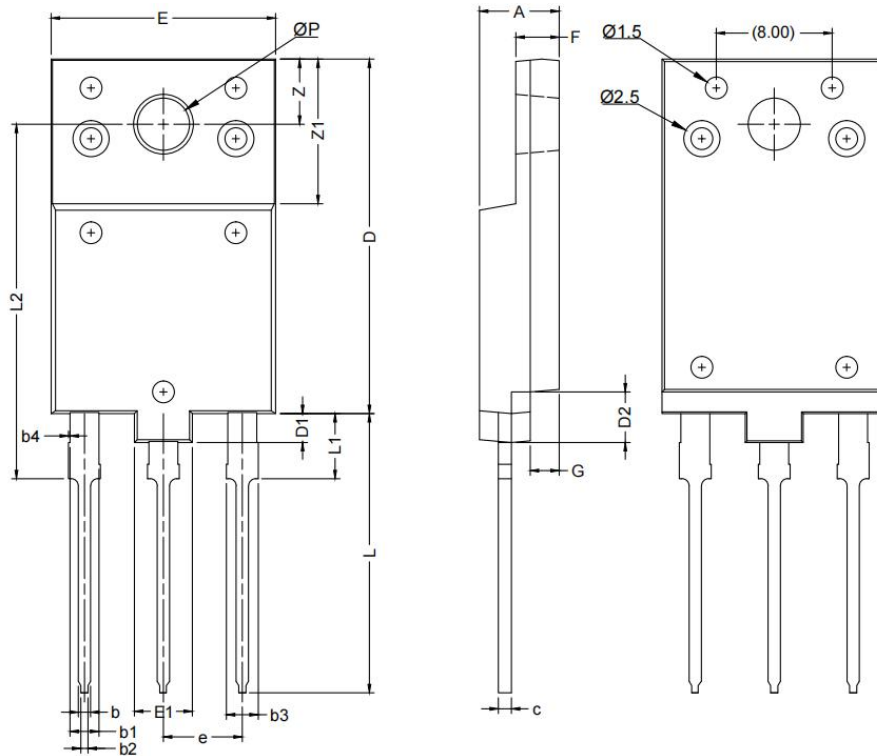
### 2) Switch Time Test Circuit:



### 3) Unclamped Inductive Switching Test Circuit & Waveforms



## TO-3PF-B Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	5.300	5.700	0.209	0.224
b	0.650	0.950	0.026	0.037
b4		0.200		0.008
C	0.800	1.000	0.031	0.039
D	24.200	24.800	0.953	0.976
D1	1.800	2.200	0.071	0.087
D2	3.300	3.700	0.130	0.146
E	15.300	15.700	0.602	0.618
E1	3.800	4.200	0.150	0.165
F	2.800	3.200	0.110	0.126
e	5.450 BSC		0.215 BSC	
L	19.000	19.600	0.748	0.772
L1	4.200	4.800	0.165	0.189
L2	24.200	24.800	0.953	0.976
P	3.400	3.800	0.134	0.150
Z	4.300	4.700	0.169	0.185
Z1	9.700	10.300	0.382	0.406
G	1.800	2.200	0.071	0.087
S	3.100	3.500	0.122	0.138

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